

Abstract of the Disclosure

A wafer processing method for dividing a wafer having optical devices that are formed in a plurality of areas sectioned by dividing lines formed in a lattice pattern on the front surface, along the dividing lines, which comprises
5 a laser beam application step of applying a laser beam to the wafer along the dividing lines from the side of back surface thereof to form grooves having a predetermined depth in the back surface; a protective sheet affixing step of affixing
10 a protective sheet to the front surface of the wafer having the grooves in the back surface; a dividing step of dividing the wafer having the protective sheet affixed to the front surface along the grooves; and a grinding step of grinding the back surface of the wafer divided along the grooves in
15 a state of the protective sheet being affixed to the wafer, to remove the grooves.